

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Hsin-Chang Hsiung	01/15/2010
Shu-Lin Ho	01/15/2010
RECEIVING PARTY DATA	
Name:	Wisepal Technologies, Inc.
Street Address:	No. 26, Zih Lian Road, Tree Valley Park, Sinshih
City:	Tainan County
State/Country:	TAIWAN
Name:	Core Precision Material Co., Ltd.
Street Address:	No. 68-27, Pusin Village, Pusin, Dayuan Township
City:	Taoyuan County
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12701615
CORRESPONDENCE DATA	
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PATENT
REEL: 023908 FRAME: 0720

Total Attachments: 2
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ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

ASSIGNOR(S) (Inventors):

Name: Hsin-Chang Hsiung Nationality: TW

Name: Shu-Lin Ho Nationality: TW

Hereby sells, assigns and transfers to

ASSIGNEE(S):

Name: Wisepal Technologies, Inc.

Address: No. 26, Zih Lian Road, Tree Valley Park, Sinshih, Tainan County 74148, Taiwan, R.O.C.

Name: Core Precision Material Co., Ltd.

Address: No. 68-27, Pusin Village, Pusin, Dayuan Township, Taoyuan County, Taiwan, R.O.C.

and the successors and assignees of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

"SEMICONDUCTOR DEVICE AND FABRICATING METHOD THEREOF"

Which is found in :

- (a) + U.S. patent application executed on even date
- (b) _____ U.S. patent application executed on _____
- (c) _____ U.S. application serial no. _____
- (d) _____ patent no. _____ issued _____

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this JAN 15 2010 (Date of signing). (請發明人務必簽署上列日期。)

(Type name of inventor)

Signature of INVENTOR

Hsin-Chang Hsiung

Hsin-Chang Hsiung

Shu-Lin Ho

Ho, Shu-Lin